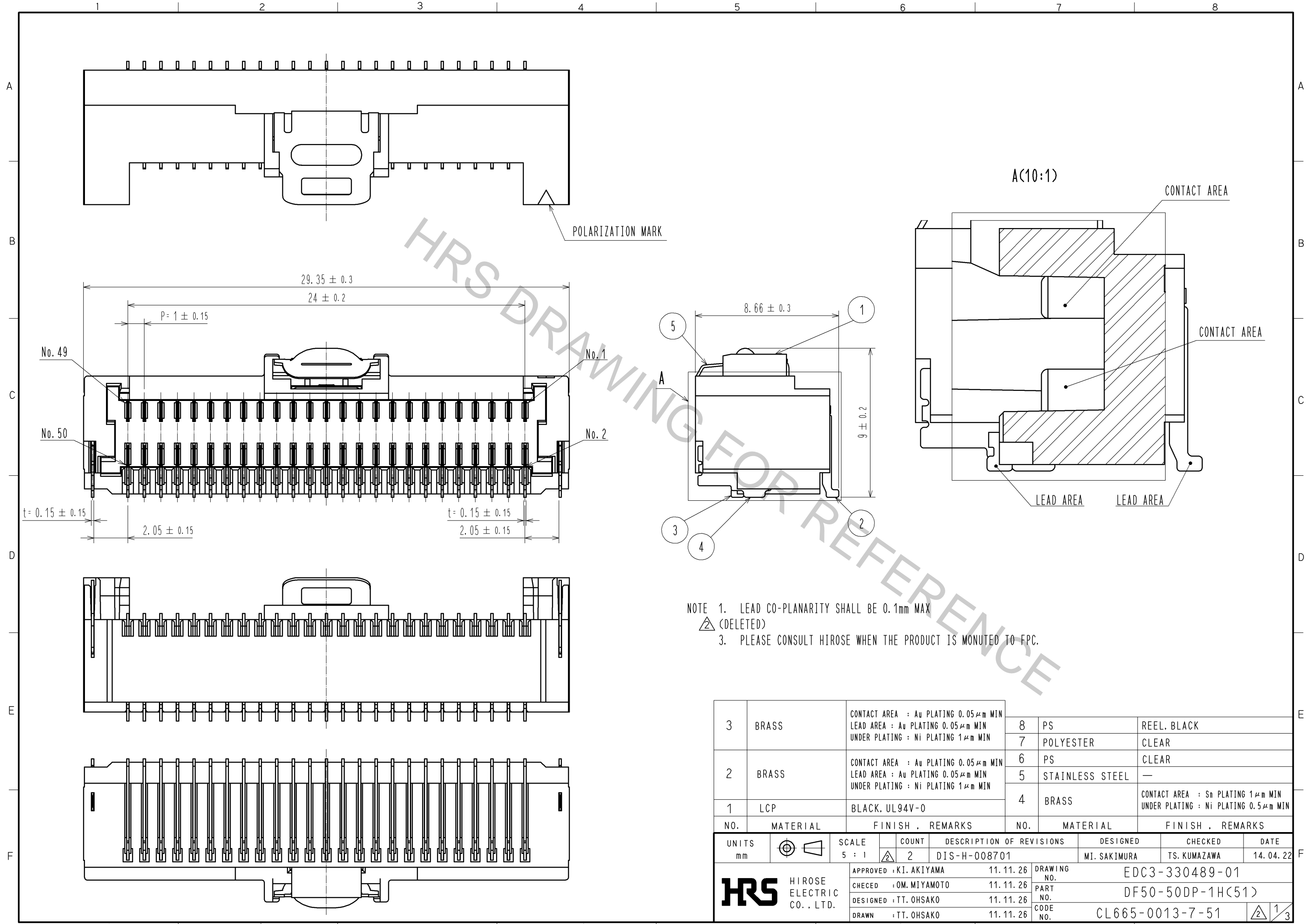


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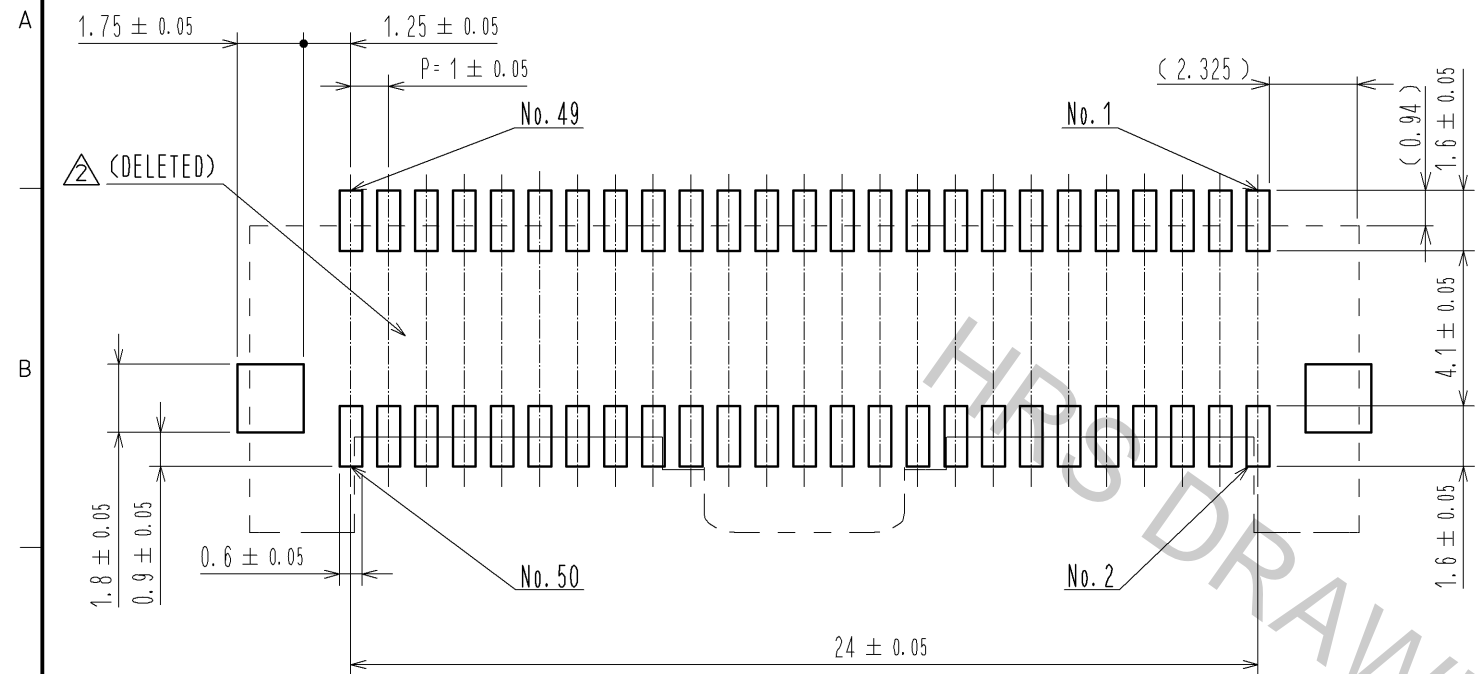


NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX  
 (DELETED)  
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	8	PS	REEL, BLACK
			7	POLYESTER	CLEAR
2	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	6	PS	CLEAR
			5	STAINLESS STEEL	—
1	LCP	BLACK, UL94V-0	4	BRASS	CONTACT AREA : Sn PLATING 1 μm MIN UNDER PLATING : Ni PLATING 0.5 μm MIN
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE 5 : 1	COUNT 2	DESCRIPTION OF REVISIONS DIS-H-008701	
DESIGNED MI. SAKIMURA		CHECKED TS. KUMAZAWA		DATE 14. 04. 22	
APPROVED : KI. AKIYAMA		11. 11. 26		DRAWING NO. EDC3-330489-01	
CHECKED : OM. MIYAMOTO		11. 11. 26		PART NO. DF50-50DP-1H(51)	
DESIGNED : TT. OHSAKO		11. 11. 26		CODE NO. CL665-0013-7-51	
DRAWN : TT. OHSAKO		11. 11. 26			

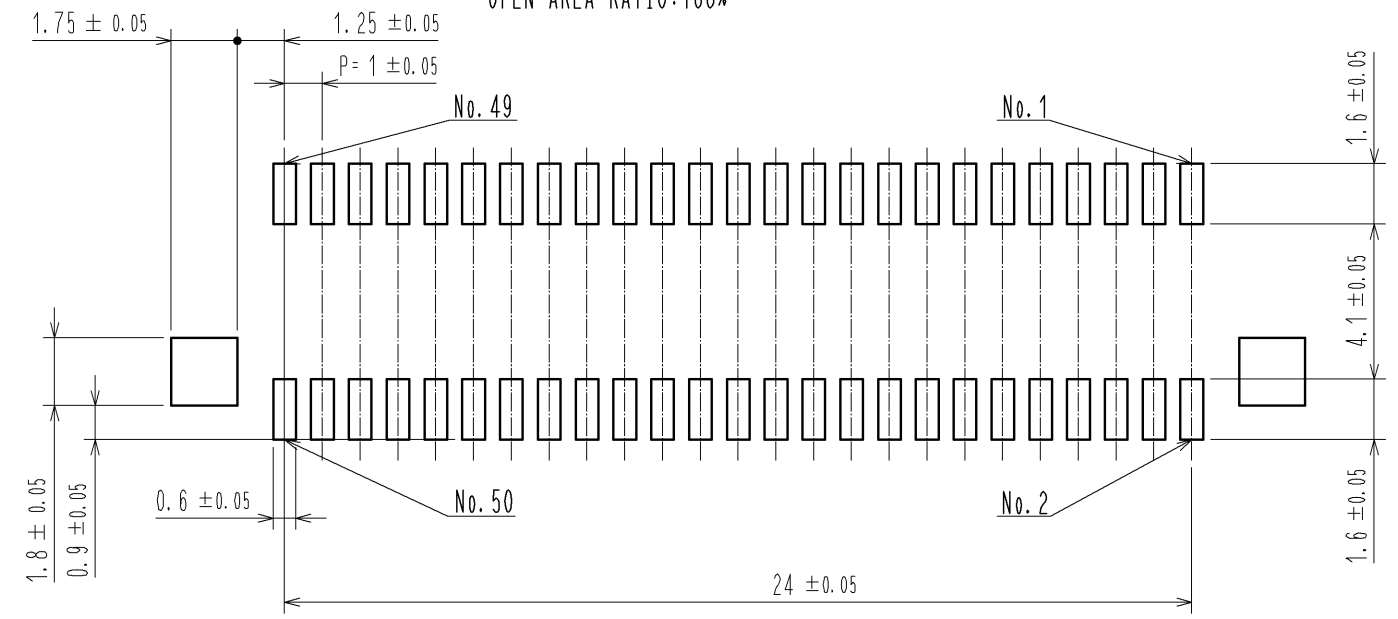
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RECOMMENDED PCB LAYOUT  
(MOUNTING SURFACE SIDE) (FREE)

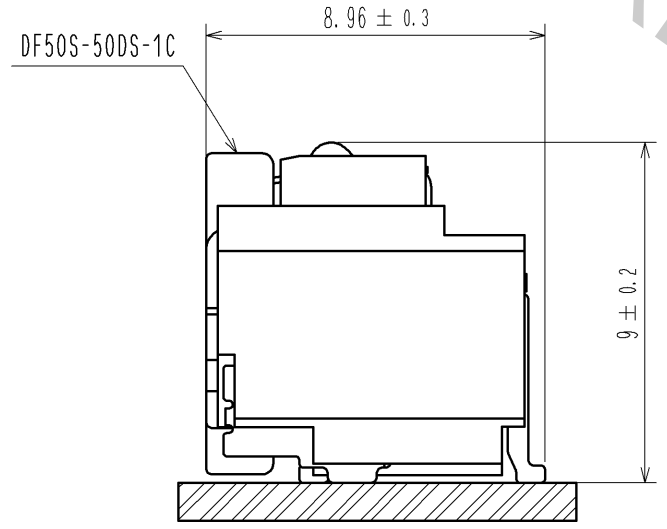
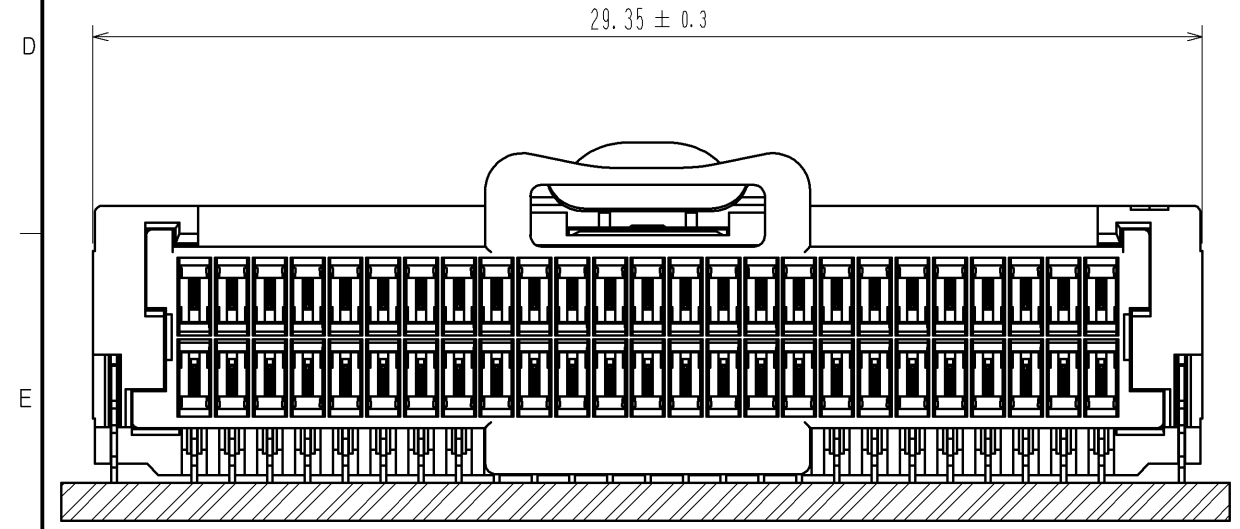


RECOMMENDED METAL MASK (FREE)

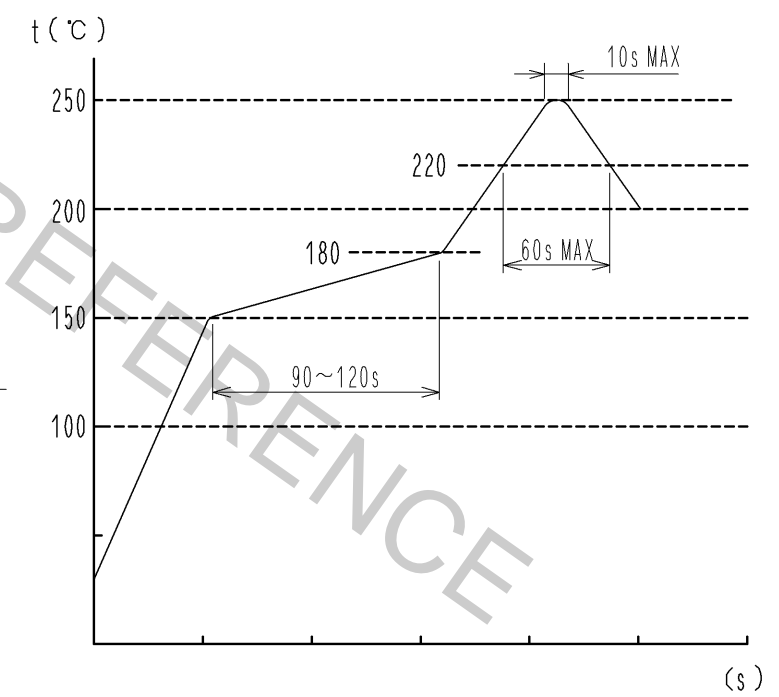
THICKNESS : 0.1mm  
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



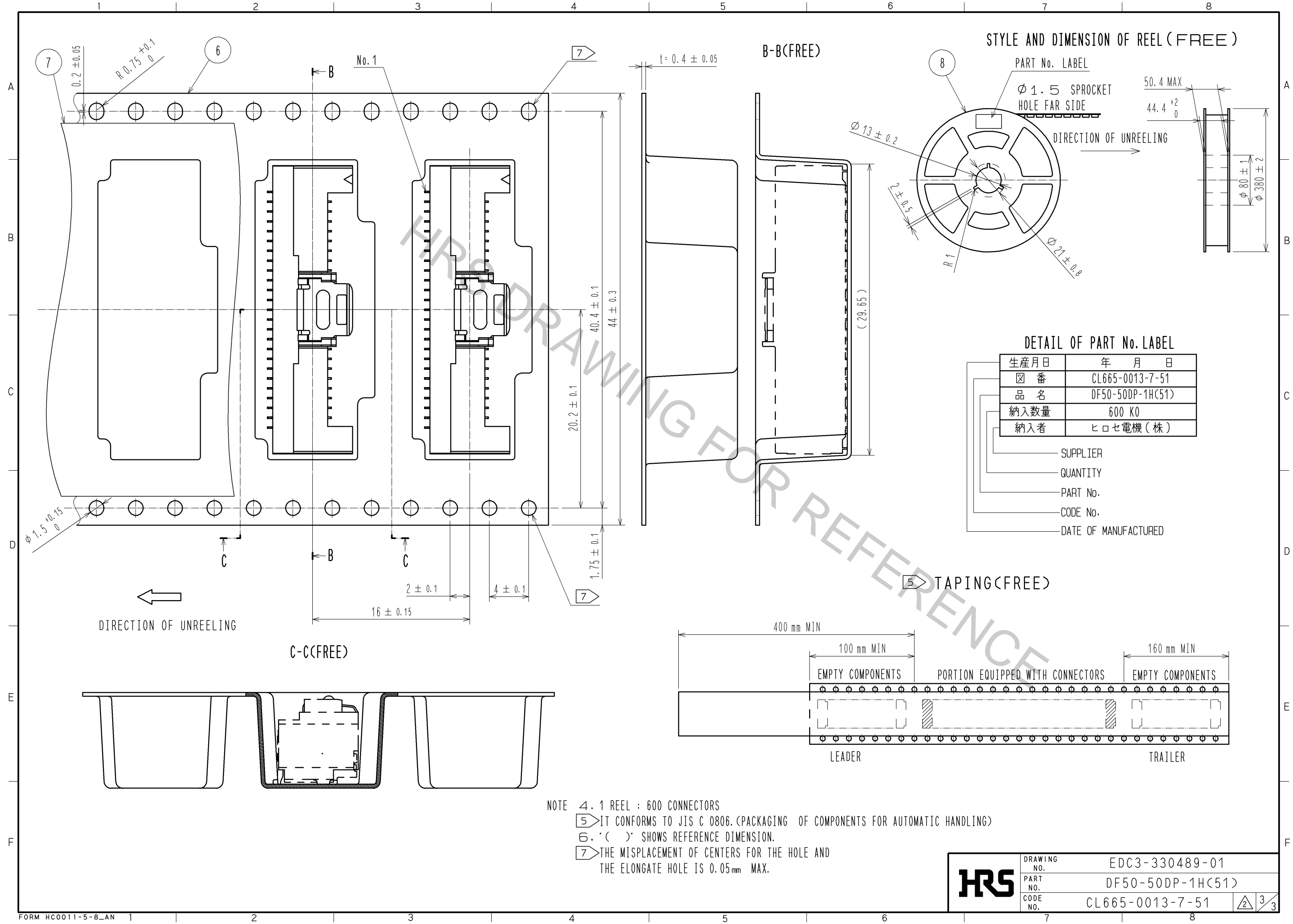
REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING MATERIAL etc..

<b>HRS</b>	DRAWING NO.	EDC3-330489-01
	PART NO.	DF50-50DP-1H(51)
	CODE NO.	CL665-0013-7-51
		2/3



<b>HRS</b>	DRAWING NO.	EDC3-330489-01
	PART NO.	DF50-50DP-1H(51)
	CODE NO.	CL665-0013-7-51
		3/3